IN THE CLAIMS:

Please substitute the following claims for the same-numbered claims in the application:

1. (Currently Amended) An apparatus ~~for separating two parts of a workpiece, wherein said two parts are connected by interconnects, said apparatus~~ comprising:

a frame;

at least one partial-circle structure above said frame; and

at least one temperature-sensitive release ~~in contact with~~ operably connected to said at least one partial-circle structure[[s]],

wherein said frame is configured to hold a workpiece having two parts connected by interconnects such that said at least one partial-circle structure is positioned to pass between said two parts and break said interconnects when released by said at least one temperature-sensitive release.

2. (Currently Amended) The apparatus in claim 1, wherein said at least one partial-circle structure comprises a plurality of partial-circle structures ~~in contact with~~ operably connected to a plurality of temperature-sensitive releases, and

each of said temperature-sensitive releases are different, such that each of said partial-circle structures is released at a different temperature.

3. (Currently Amended) The apparatus in claim 1, wherein said at least one partial-circle

structure comprises a plurality of partial-circle structures ~~in contact with~~ operably connected to a plurality of temperature-sensitive releases, and

wherein rotational paths of said partial-circle structures partially overlap.

4. (Currently Amended) The apparatus in claim 1, wherein said at least one partial-circle structure comprises a plurality of partial-circle structures ~~in contact with~~ operably connected to a plurality of temperature-sensitive releases, and

wherein said workpiece is positioned between said partial-circle structures.

5. (Currently Amended) The apparatus in claim 1 [[4]], wherein said at least one partial-circle structure[[s]] comprises less than a three-quarter portion of a disc that is approximately .01 inches thick ~~rotate around axis external to said workpiece~~.

6. (Cancelled).

7. (Original) The apparatus in claim 1, wherein said temperature-sensitive release is adapted to release said partial-circle structure at a temperature above a melting point of said interconnects.

8. (Currently Amended) An apparatus ~~for separating two parts of a workpiece, wherein said two parts are connected by interconnects, said apparatus~~ comprising:

a frame;

~~partial circle structures~~ at least one solder removal structure comprising one of a partial-disk, a blade and a knife above said frame; and

at least one temperature-sensitive release[[s]] operably connected said at least one solder removal structure ~~in contact with said partial circle structures~~,

wherein said frame is configured to hold a workpiece, comprising two parts connected by solder balls, such that said at least one solder removal structure is ~~partial-circle structures are~~ positioned to pass between said two parts and break said solder balls ~~interconnects~~ when released by said at least one temperature-sensitive release[[s]] and,

wherein said two parts comprise one of a chip and substrate and a substrate and carrier~~;~~ ~~and~~

~~reservoirs positioned to receive material from said interconnects broken by said partial circle structures~~.

9. (Currently Amended) The apparatus in claim 8, wherein said at least one solder removal structure comprises a plurality of solder removal structures operably connected to a plurality of temperature-sensitive releases, and wherein each of said temperature-sensitive releases are different, such that each of said ~~partial circle structures~~ solder removal structures is released at a different temperature and wherein rotational paths of said solder removal structures ~~partial circle structures~~ partially overlap.

10. (Cancelled).

11. (Currently Amended) The apparatus in claim 8, wherein said at least one solder removal structure comprises a plurality of solder removal structures operably connected to a plurality of temperature-sensitive releases, and wherein said workpiece is positioned between said solder removal structures ~~partial circle structures~~.

12-13. (Cancelled).

14. (Currently Amended) The apparatus in claim 9 ~~8~~, wherein said temperature-sensitive releases are adapted to release said solder removal structures ~~partial-circle structures~~ at temperatures above a melting point of said solder balls ~~interconnects~~.

15. (Currently Amended) An apparatus ~~for separating two parts of a workpiece, wherein said two parts are connected by interconnects, said apparatus~~ comprising:

a frame having an upper part and a lower part;

at least one axle extending vertically through said upper part of said frame;

~~rotationally biased~~ at least one partial-circle structure[[s]] connected to said at least one axle such that rotation of said at least one axle rotates said at least one partial-circle structure; and

at least one temperature-sensitive release[[s]] operably connected to said at least one axle,

wherein said at least one axle is spring-loaded to rotate when released by said at least one temperature sensitive release and, ~~in contact with said partial-circle structures~~,

wherein said frame is adapted to hold a workpiece, comprising two parts connected by interconnects, such that said at least one partial-circle structure[[s]] ~~are~~ is positioned ~~to rotate,~~ to pass between said two parts and to break said interconnects, when rotated ~~released by said temperature sensitive releases~~.

16. (Currently Amended) The apparatus in claim 15, wherein said at least one axle comprises a plurality of axles, wherein said at least one partial-circle structure comprises a plurality of partial-circle structures, wherein said at least one temperature-sensitive release comprises a plurality of temperature-sensitive releases, wherein each one of said axles are connected to corresponding ones of said temperatures-sensitive releases and said partial-circles structures and, wherein each of said temperature-sensitive releases are different, such that each of said partial-circle structures is ~~released~~ rotated at a different temperature and wherein rotational paths of said partial-circle structures partially overlap.

17. (Cancelled).

18. (Currently Amended) The apparatus in claim 15, wherein said at least one partial-circle structure comprises a plurality of partial-circle structures and wherein said ~~workpiece~~ device is positioned between said partial-circle structures.

19-20. (Cancelled).

21. (New) The apparatus of claim 1, wherein said two parts comprise one of a chip and substrate and a substrate and carrier and wherein said frame further comprises at least one

reservoir positioned to receive material from said interconnects broken by said at least one partial-circle structure.

22. (New) The apparatus of claim 8, wherein said frame further comprises at least one reservoir positioned to receive material from said solder balls broken by said at least one solder removal structure.

23. (New) The apparatus of claim 15, wherein said two parts comprise one of a chip and substrate and a substrate and carrier and wherein said frame further comprises at least one reservoir positioned to receive material from said interconnects broken by said at least one partial-circle structure.

24. (New) The apparatus of claim 1, further comprising at least one axle extending vertically through an upper part said frame and connected to said at least one partial circle structure, wherein said at least one axle is spring-loaded to rotate such that said at least one partial circle structure rotates and passes between said two parts and breaks said interconnects when released by said at least one temperature sensitive release.

25. (New) The apparatus of claim 8, further comprising at least one axle extending vertically through an upper part of said frame and connected to said at least one solder removal structure, wherein said at least one axle is spring-loaded to rotate such that said at least one solder removal structure rotates and passes between said two parts and breaks said solder balls when released by said at least one temperature sensitive release.

26. (New) The apparatus of claim 15, wherein said at least one partial-circle structure comprises less than a three-quarter portion of a disc that is approximately .01 inches thick.

27. (New) The apparatus of claim 15, further comprising:

at least one stop member connected to said frame for limiting rotation of said at least one axle; and

at least one torsion spring adjuster connected to said at least one axle for returning said axle to a spring-loaded position after release by said at least one temperature sensitive release.